Specification of Thermoelectric Module TEC4-127-71-31-17-03T1

Description

The TEC4-127-71-31-17-03T1 is a multistage module designed for greater temperature differential cooling, good for cooling and heating up to 100 °C applications. It is a 127-71-31-17 couples module in size of 15mm×15mm (top)/40mm ×40mm (bottom). If higher operation or processing temperature is required, please specify, we can design and manufacture according to your special requirements.

Features

- High Temperature Differential
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

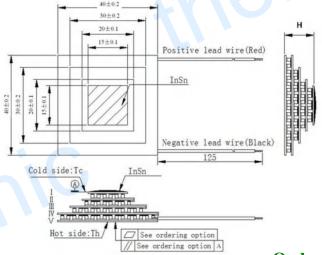
Application

- Infrared (IR) Sensors
- CCD Sensor
- Gas Analyzers
- Calibration Equipment
- CPU cooler and scientific instrument
- Photonic and medical systems
- Guidance Systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N2	
DT _{max} (°C)	112	126	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	14.6	16.4	Voltage applied to the module at DT _{max}	
I _{max} (Amps)	3.4	3.4	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	7.4	8.1	Cooling capacity at cold side of the module under DT= 0 °C	
AC resistance (Ohms)	4.2	4.7	The module resistance is tested under AC	
Tolerance	10%		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

- A. Solder:
- 1. T100: BiSn (Tmelt=138°C)
- 2. T200: CuAgSn (Tmelt = 217° C) 2.
- 3. T240: SbSn (Tmelt = 240°C)

C. Ceramics:

- 1. Alumina (Al₂O₃, white 96%)
- 2. Aluminum Nitride (AlN)

B. Sealant:

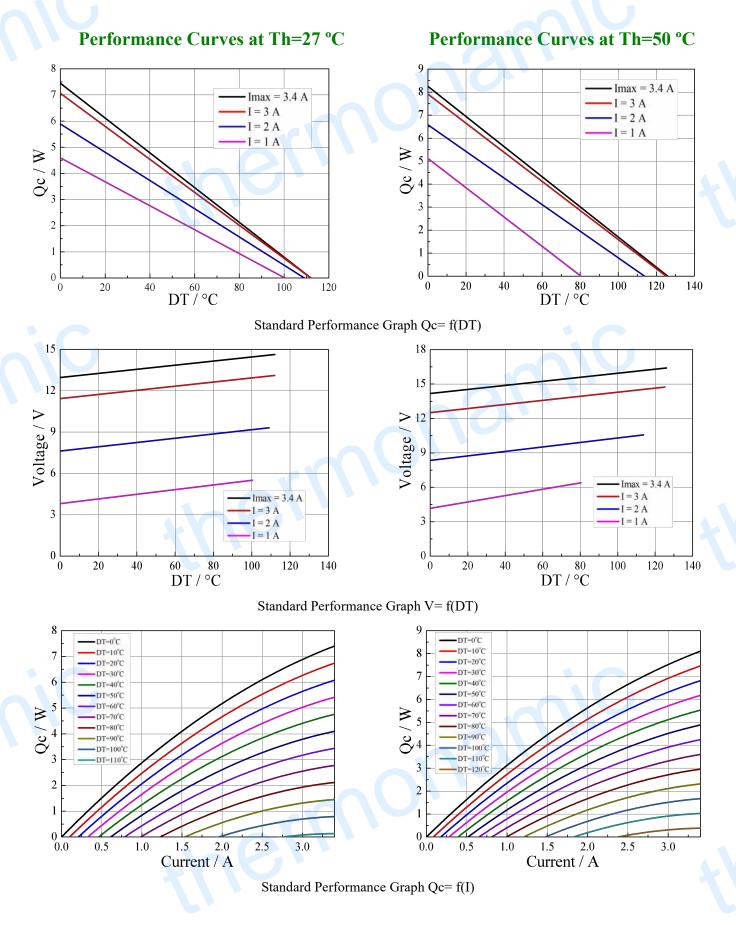
- 1. NS: No sealing (Standard)
- = 217°C) 2. SS: Silicone sealant
 - 3. EPS: Epoxy sealant
 - **D.** Ceramics Surface Options:
 - 1. Blank ceramics (not metalized)
 - 2. Metalized

Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length	
TF	0: 13.8±0.4	0: 0.08/0.08	125±3/Specify	

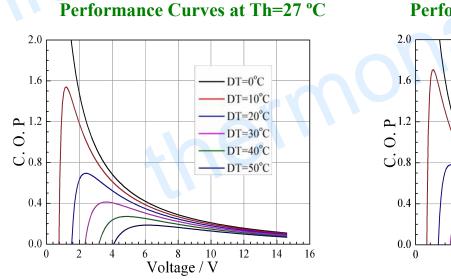
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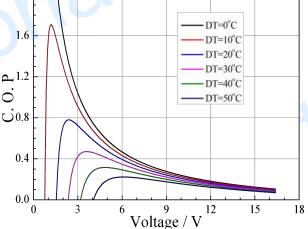


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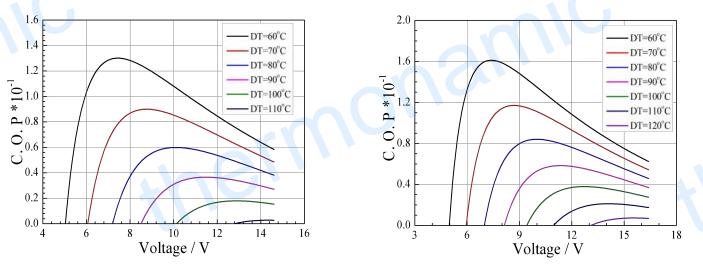
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Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 50 °C



Standard Performance Graph COP = f(V) of DT ranged from 60 to 110/120 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation or storage module below 100 °C
- \bullet Operation below $I_{max} \text{ or } V_{max}$
- Work under DC

Note: All specifications subject to change without notice.